

Title (en)

Wooden material with conductive surface

Title (de)

Holzwerkstoff mit ableitfähiger Oberfläche

Title (fr)

Matériau à base de bois comprenant une surface conductrice

Publication

**EP 1681103 B1 20101020 (DE)**

Application

**EP 06000691 A 20060113**

Priority

DE 102005002059 A 20050114

Abstract (en)

[origin: EP1681103A2] A panel (A) of wooden material (WM), having a surface coating comprising an undercoat (applied to WM) and at least one lacquer layer (LL) hardened by UV-light or an electron beam (the overall thickness of the LL('s) being less than 120  $\mu$ m), includes at least one functional component (I), integrated in LL('s) or in the form of a functional layer which is external, under LL('s) or between at least two LL's. Independent claims are included for: (1) a panel (A') of WM, having a coating of lacquer on at least part of the side opposite to the surface coated; (2) a method for coating WM by applying at least two layers of UV-hardenable lacquer, where the first layer is subjected to UV treatment to start hardening of the lacquer, the second layer(s) is/are applied before the first layer has hardened completely and complete hardening of the second layer(s) using UV light is commenced after applying the last layer; and (3) apparatus for coating (specifically lacquering) panels, in which the panels are transported to and from a processing unit, the coating is applied and the coating is partially or completely hardened, where (a) application and hardening devices arranged in direct succession are combined to give a processing unit, (b) at least two such processing units are provided and (c) a processing unit for applying functional layer(s) is provided before, between or after processing units for applying at least two LL's.

IPC 8 full level

**B05D 7/06** (2006.01)

CPC (source: EP)

**B05D 7/06** (2013.01); **B44C 5/043** (2013.01); **D21H 27/28** (2013.01); **E04F 15/02** (2013.01); **B05D 5/12** (2013.01); **B05D 7/52** (2013.01); **B05D 2203/22** (2013.01); **B05D 2601/20** (2013.01); **E04F 2290/048** (2013.01)

Cited by

US9783996B2; EP2537597A1; EP3090812A1; JP2011522138A; BE1025875B1; EP2562003A3; AU2008328030B2; AU2008328030C1; US2009155612A1; EP3072653A1; US10214913B2; US11794460B2; WO2009065769A3; WO2019135140A1; US10493729B2; US11135814B2; US10513094B2; US10926509B2; US11313123B2; US11633884B2; US10981362B2; US11738540B2; US10017950B2; US11401718B2; US10828881B2; US11167533B2; US11904588B2; US10286633B2; US10899166B2; US10800186B2; US11072156B2; US11235565B2; US11485126B2; US7811489B2; US10913176B2; US11046063B2; US12070873B2; US8349234B2; US10392812B2; US11905717B2; US10100535B2; US10988941B2; US11318726B2; US11370209B2; US11890847B2; US10315219B2; US10442164B2; US10857765B2; US11040371B2; US12103273B2; US9573343B2; US10307984B2; US10344379B2; US10967608B2; US11541630B2; US11597187B2; US11975508B2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**EP 1681103 A2 20060719**; **EP 1681103 A3 20060927**; **EP 1681103 B1 20101020**; AT E485114 T1 20101115; DE 102005002059 A1 20060727; DE 502006008108 D1 20101202; EP 2192229 A2 20100602; EP 2192229 A3 20120111; EP 2192229 B1 20130724; ES 2353895 T3 20110308; ES 2428416 T3 20131107; PL 1681103 T3 20110429; PL 2192229 T3 20131231

DOCDB simple family (application)

**EP 06000691 A 20060113**; AT 06000691 T 20060113; DE 102005002059 A 20050114; DE 502006008108 T 20060113; EP 10150990 A 20060113; ES 06000691 T 20060113; ES 10150990 T 20060113; PL 06000691 T 20060113; PL 10150990 T 20060113